



SOT1236

Plastic, single-ended surface-mounted package (LFAK88D;
Power-SO8); 4 leads

25 November 2016

Package information

1. Package summary

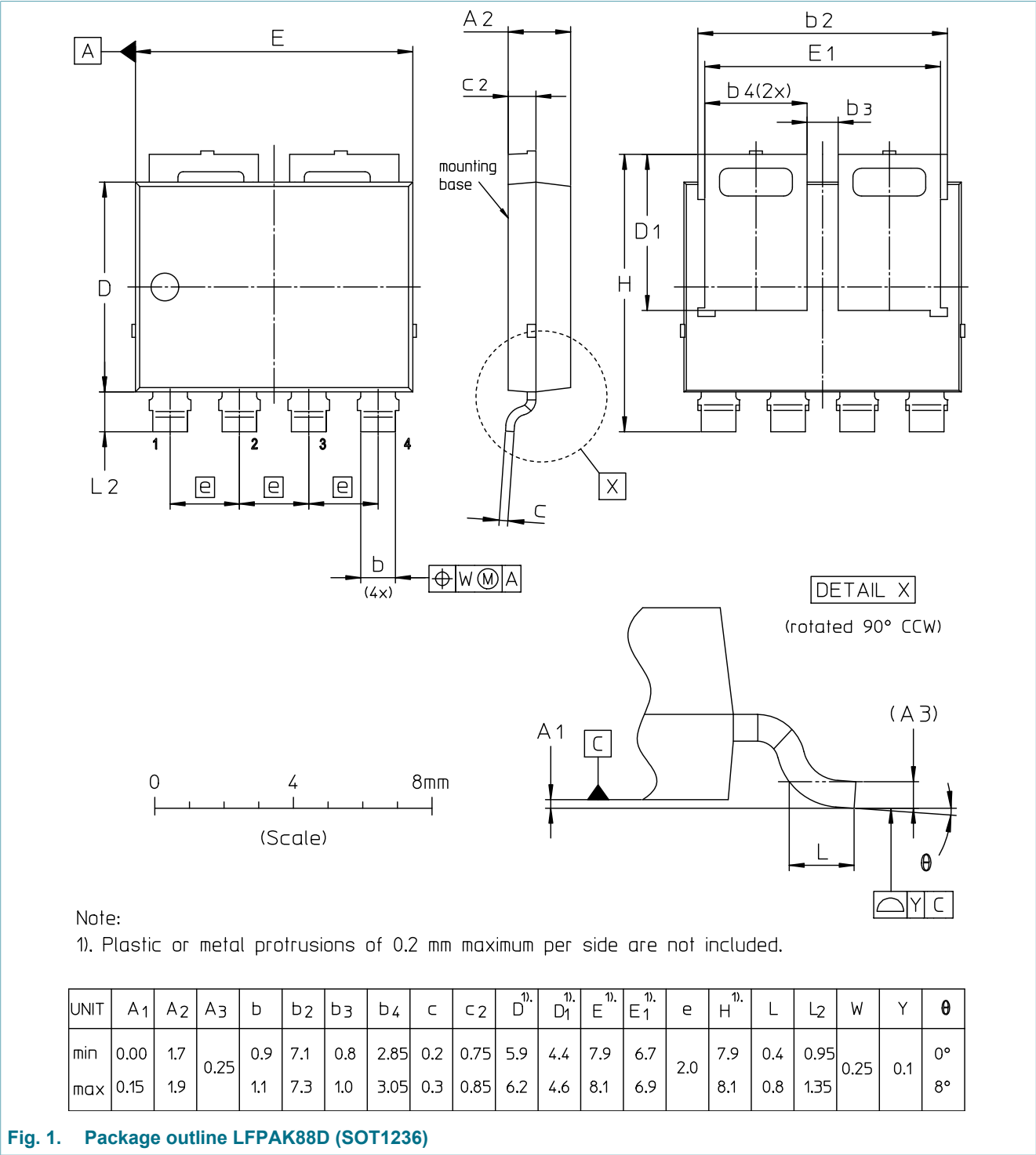
Terminal position code	S (single)
Package type descriptive code	LFAK88D
Package type industry code	LFAK88D
Package style descriptive code	NA
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-6-2016
Manufacturer package code	SOT1236

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6.15	-	6.3	6.45	mm
E	package width		7.9	-	8	8.1	mm
A	seated height		1.65	-	1.75	1.85	mm
e	nominal pitch		-	-	2	-	mm
n ₂	actual quantity of termination		-	-	4	-	



2. Package outline



3. Legal information

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